

16. (New) A circuit board according to claim 13, wherein said forming comprises disposing masses of solder paste on the joining surface of the substrate, and heating and melting the masses of solder paste.

17. (New) A circuit board according to claim 13, wherein a coplanarity per unit length of the solder bumps is 0.5 μm or less.

18. (New) A circuit board according to claim 13, wherein circular pads are interposed between the respective solder bumps and the substrate, and the tops of the solder bumps are circular and smaller in diameter than the pads.

19. (New) A circuit board according to claim 18, wherein circular pads are interposed between the respective solder bumps and the substrate, the tops of the solder bumps are nearly equal in diameter to the pads, and the height of the solder bumps is smaller than the diameter of the pads.

20. (New) A circuit board produced by the process of:
preparing a substrate having a joining surface;
disposing a plurality of masses of solder paste on the joining surface of the substrate;

disposing a jig so that a flat surface of the jig is located at a predetermined position above the masses of solder paste; and

melting the masses of solder paste to bring tops of the masses of solder paste into contact with the flat surface of the jig and thereby forming solder bumps having flattened and levelled tops.

21. (New) A circuit board according to claim 20, wherein a coplanarity per unit length of the solder bumps is 0.5 μm or less.

22. (New) A circuit board according to claim 20, wherein circular pads are interposed between the respective solder bumps and the substrate, and the tops of the solder bumps are circular and smaller in diameter than the pads.

23. (New) A circuit board according to claim 20, wherein circular pads are interposed between the respective solder bumps and the substrate, the tops of the solder bumps are nearly equal in diameter to the pads, and the height of the solder bumps is smaller than the diameter of the pads.

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24. (New) A method of producing a circuit board comprising:
preparing a substrate having a joining surface;
forming a plurality of solder bumps on the joining surface of the substrate; and
flattening and levelling tops of the solder bumps.

25. (New) A method according to claim 24, wherein said flattening and levelling comprises pressing a flat surface of a jig against the tops of the solder bumps.

C' concluded

26. (New) A method according to claim 24, wherein said flattening and levelling comprises grinding the tops of the solder bumps.

27. (New) A method according to claim 24, wherein said forming comprises disposing masses of solder paste on the joining surface of the substrate, and heating and melting the masses of solder paste

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28. (New) A method of producing a circuit board comprising:
preparing a substrate having a joining surface;
disposing a plurality of masses of solder paste on the joining surface of the substrate;
disposing a jig so that a flat surface of the jig is located at a predetermined position above the masses of solder paste; and
melting the masses of solder paste to bring tops of the masses of solder paste into contact with the flat surface of the jig and thereby forming solder bumps having flattened and levelled tops.